## **CLAIMS**

## What is claimed is:

- 1. (Currently Amended) A contactless sheet resistance measurement apparatus for measuring sheet resistance comprising:
  - a light source for illuminating the area of a semiconductor structure with an intensity modulated light,
  - a transparent conducting electrode optically coupled with the light source and used for detecting photovoltage signals inside the illuminated area,
  - a first non transparent conducting electrode used for detecting photovoltage signals outside of the illumination area, and
  - a second non transparent conducting electrode connected to a ground and installed between the transparent and first non transparent electrodes.
- 2. (Withdrawn)
- 3. (Withdrawn)
- 4. (Currently Amended) The apparatus of claim 1, wherein the transparent conducting electrode is a glass or quartz disk with an ITO coating and the first non transparent electrode is a metal ring coaxially installed to the glass or quartz disk.
- 5. (Currently Amended) The apparatus of claim 1, wherein the transparent and conducting electrode is a glass or quartz disk with an ITO coating and the first non transparent electrode is a part of the metal ring coaxially installed to the glass or quartz disk.

- 20. (New) The apparatus of claim 4, wherein the second non transparent electrode connected to the ground is a metal ring coaxially installed between the glass or quartz disk with an ITO coating and the first non transparent electrode.
- 21. (New) The apparatus of claim 5, wherein the second non transparent electrode connected to the ground is a part of the metal ring coaxially installed between the glass or quartz disk with an ITO coating and the first non transparent electrode.
- 22. (New) The apparatus of claims 4, 5, 20, or 21 wherein the illumination means comprises a light emitting diode and an optical fiber directing light onto the wafer surface.
- 23. (New) The apparatus of claims 4, 5, 20, or 21, wherein the illumination means comprises a laser and an optical fiber directing light onto the wafer surface.